

1. Description

BLG4065FUL is obtained by advanced Trench Field Stop (T-FS) technology which is characteristic with low $V_{CE(sat)}$, optimized switching performance and low gate charge Q_g . The IGBT is suitable device for Photovoltaic, UPS and high switching frequency applications.

KEY CHARACTERISTICS

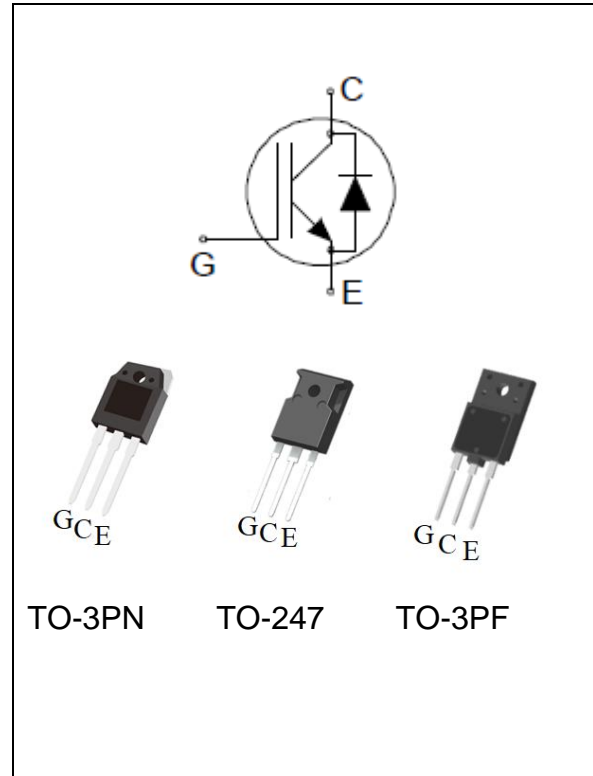
Parameter	Value	Unit
V_{CES}	650	V
I_c	40	A
$V_{CE(sat).typ}$	1.45	V

FEATURES

- Fast Switching
- LOW $V_{CE(sat)}$
- Positive temperature coefficient
- Fast recovery anti-parallel diode
- RoHS product

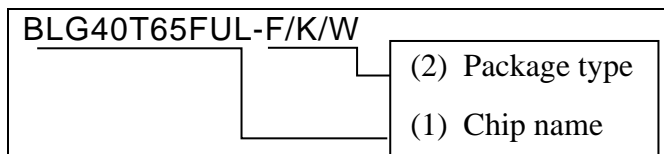
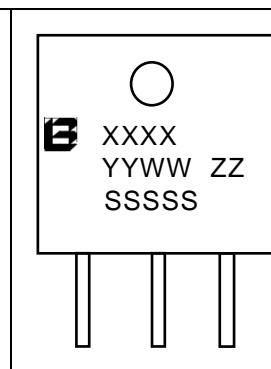
APPLICATIONS

- Photovoltaic converters
- UPS



ORDERING INFORMATION

Device Marking	Ordering Codes	Package	Product Code	Packing
40T65FUL	BLG40T65FUL-F	TO-247	G40T65FUL	Tube
	BLG40T65FUL-K	TO-3PF	G40T65FUL	Tube
	BLG40T65FUL-W	TO-3PN	G40T65FUL	Tube

<p>BLG40T65FUL-F/K/W</p>  <p>(1) BLG40T65FUL: 650V 40A (2) F:TO-247 K:TO-3PF W:TO-3PN</p>	 <p>XXXX: Product Code YYWW: Year & Week ZZ: Assembly Code SSSS: Lot Code</p>
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2. ABSOLUTE RATINGS

Symbol	Parameter	TO-3PN/TO-247	TO-3PF	Units
V_{CES}	Collector-Emitter Voltage	650	650	V
I_C	Collector Current @ $T_C=25^\circ\text{C}$	80	80	A
	Collector Current @ $T_C=100^\circ\text{C}$	40	40	A
I_{CM}	Pulsed Collector Current, tp limited by T_{Jmax}	160	160	A
I_F	Diode Continuous Forward Current @ $T_C=25^\circ\text{C}$	40	40	A
	Diode Continuous Forward Current @ $T_C=100^\circ\text{C}$	20	20	A
I_{FM}	Diode Maximum Forward Current, limited by T_{Jmax}	80	80	A
V_{GES}	Gate-Emitter Voltage	± 30	± 30	V
t_{SC}	Short circuit withstand time $V_{GE}=15\text{V}$, $V_{CC}\leq 400\text{V}$, Allowed number of short circuits < 1000, Times between short circuits: $\geq 1.0\text{s}$, $T_J \leq 175^\circ\text{C}$	8		μs
P_D	Power Dissipation @ $T_C=25^\circ\text{C}$	300	50	W
T_{Jmax} , T_{stg}	Operating Junction and Storage Temperature Range	175, -55 to 175		$^\circ\text{C}$
T_L	Maximum Temperature for Soldering	260		$^\circ\text{C}$

3. Thermal characteristics

Symbol	Parameter	TO-3PN/TO-247	TO-3PF	Units
$R_{\theta JC}$	Junction-to-Case (IGBT)	0.5	3.0	$^\circ\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case (Diode)	0.8	2.0	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Junction-to-Ambient	40	40	$^\circ\text{C}/\text{W}$

4. Electrical Characteristics

at $T_C = 25^\circ\text{C}$, unless otherwise specified

Static Characteristics

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
V_{CES}	Collector-Emitter Breakdown Voltage	$V_{GE} = 0\text{V}$, $I_C = 250\mu\text{A}$	650	--	--	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	$V_{GE} = 15\text{V}$, $I_C = 40\text{A}$ $T_J = 25^\circ\text{C}$	--	1.45	1.85	V
		$T_J = 125^\circ\text{C}$	--	1.65	--	
		$T_J = 175^\circ\text{C}$	--	1.75	--	

$V_{GE(TH)}$	Gate Threshold Voltage	$V_{CE} = V_{GE}, I_C = 1mA$	4.7	5.5	6.2	V
V_F	Diode Forward Voltage	$I_F=20A$ $T_J=25^\circ C$ $T_J=125^\circ C$ $T_J=175^\circ C$	--	2.20 1.80 1.65	2.80 -- --	V
I_{CES}	Collector-Emitter Leakage Current	$V_{CE} = 650V,$ $V_{GE} = 0V$	--	--	25	μA
$I_{GES(F)}$	Gate-Emitter Forward Leakage Current	$V_{GE} = +30V$	--	--	200	nA
$I_{GES(R)}$	Gate-Emitter Reverse Leakage Current	$V_{GE} = -30V$	--	--	-200	nA
Pulse width $t_p \leq 300\mu s, \delta \leq 2\%$						

Dynamic Characteristics

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
C_{iss}	Input Capacitance	$V_{GE}=0V$ $V_{CE}=25V$ $f=1.0MHz$	--	2122	--	pF
C_{oss}	Output Capacitance		--	124	--	
C_{rss}	Reverse Transfer Capacitance		--	23	--	
Q_G	Gate charge	$V_{CC}=520V$ $I_{CE}=20A$ $V_{GE}=15V$	--	110	--	nC
Q_{GC}	Gate-emitter charge		--	55	--	
Q_{GE}	Gate-collector charge		--	22	--	
$I_{C(SC)}$	Short circuit collector current Max.1000 short circuits, Times between short circuits: $\geq 1.0s$	$V_{GE}=15.0V, V_{CC} \leq 400V,$ $t_{sc} \leq 8\mu s, T_J \leq 175^\circ C$		320		A

IGBT Switching Characteristics, at $T_J=25^\circ C$

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
$t_{d(on)}$	Turn-on Delay Time	$I_C = 40A$ $V_{CE} = 400V$ $V_{GE} = 15V$ $R_G = 5\Omega$ $T_J = 25^\circ C$ Inductive Load	--	20	--	ns
t_r	Rise Time		--	33	--	
$t_{d(off)}$	Turn-Off Delay Time		--	112	--	
t_f	Fall Time		--	66	--	
E_{on}	Turn-On Switching Loss		--	0.65	--	mJ
E_{off}	Turn-Off Switching Loss		--	0.68	--	
E_{ts}	Total Switching Loss		--	1.33	--	

IGBT Switching Characteristics, at $T_J=175^\circ\text{C}$

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
$t_{d(on)}$	Turn-on Delay Time	$I_C = 40\text{A}$ $V_{CE} = 400\text{V}$ $V_{GE} = 15\text{V}$ $R_G = 5\Omega$ $T_J = 175^\circ\text{C}$ Inductive Load	--	19	--	ns
t_r	Rise Time		--	34	--	
$t_{d(off)}$	Turn-Off Delay Time		--	148	--	
t_f	Fall Time		--	112	--	
E_{on}	Turn-On Switching Loss		--	0.87	--	mJ
E_{off}	Turn-Off Switching Loss		--	0.89	--	
E_{ts}	Total Switching Loss		--	1.76	--	

Diode Characteristics, at $T_J=25^\circ\text{C}$

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
Q_{rr}	Reverse Recovery Charge	$I_F = 20\text{A}$, $di/dt = 200\text{A}/\mu\text{s}$, $T_J = 25^\circ\text{C}$	--	97	--	ns
			--	109	--	nC
			--	1.8	--	A
Q_{rr}	Reverse Recovery Charge	$I_F = 40\text{A}$, $di/dt = 200\text{A}/\mu\text{s}$, $T_J = 25^\circ\text{C}$	--	127	--	ns
			--	326	--	nC
			--	4.8	--	A

Diode Characteristics, at $T_J=175^\circ\text{C}$

Symbol	Parameter	Test Conditions	Values			Units
			Min.	Typ.	Max.	
T_{rr}	Reverse Recovery Time	$I_F = 20\text{A}$, $di/dt = 200\text{A}/\mu\text{s}$, $T_J = 175^\circ\text{C}$	--	147	--	ns
Q_{rr}	Reverse Recovery Charge		--	742	--	nC
I_{rrm}	Reverse Recovery Current		--	7.8	--	A
T_{rr}	Reverse Recovery Time	$I_F = 40\text{A}$, $di/dt = 200\text{A}/\mu\text{s}$, $T_J = 175^\circ\text{C}$	--	158	--	ns
Q_{rr}	Reverse Recovery Charge		--	870	--	nC
I_{rrm}	Reverse Recovery Current		--	9	--	A

5. Characteristics Curves

Figure 1. Forward Bias Safe Operating Area for TO247/TO3PN

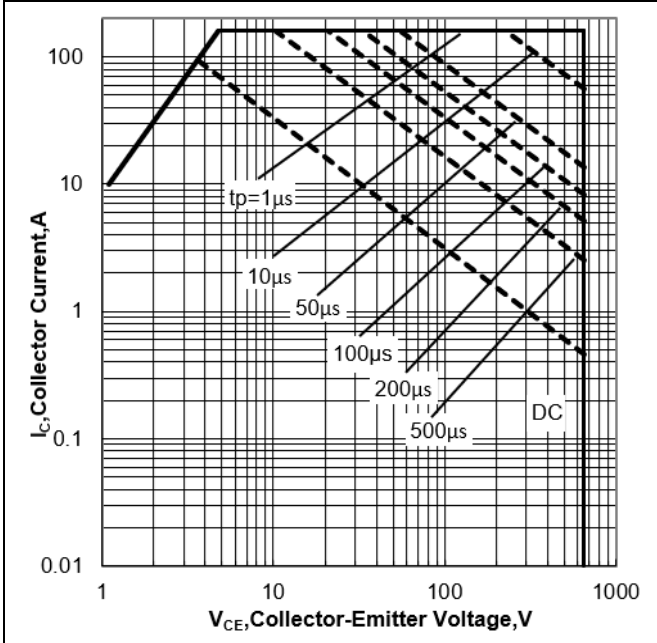


Figure 2. Forward Bias Safe Operating Area for TO3PF

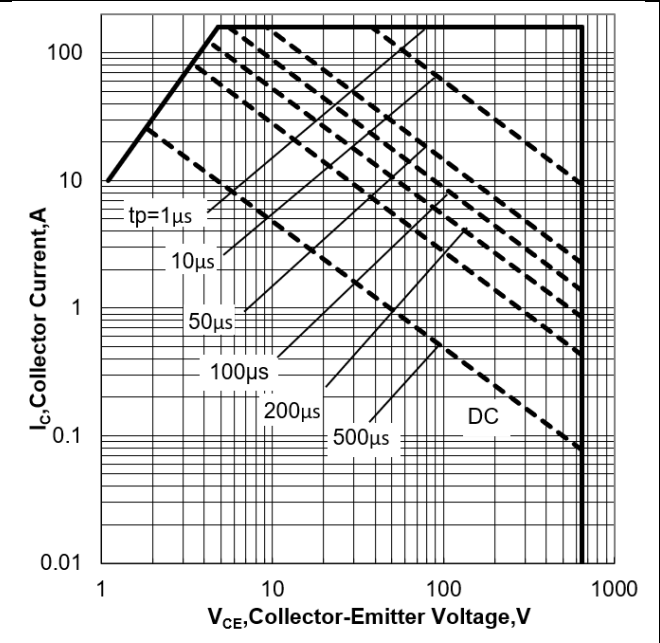


Figure 3. Power Dissipation vs Case Temperature for TO247/TO3PN

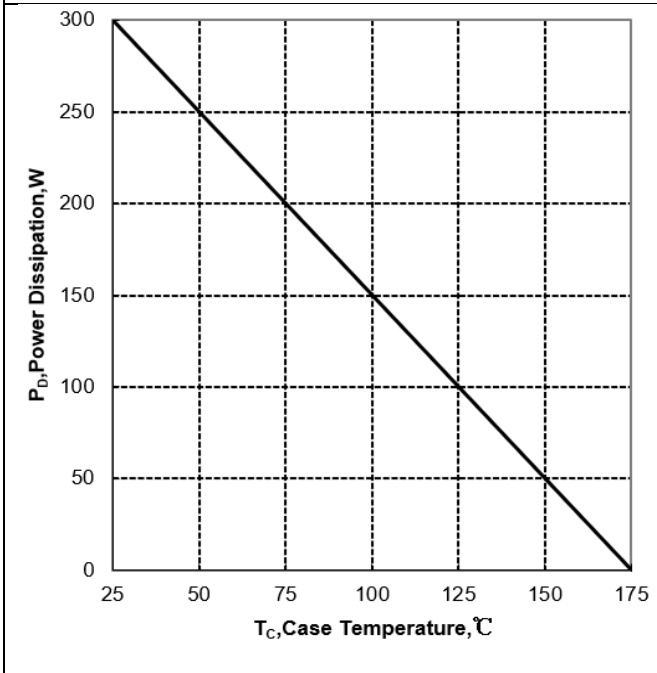


Figure 4. Power Dissipation vs Case Temperature for TO3PF

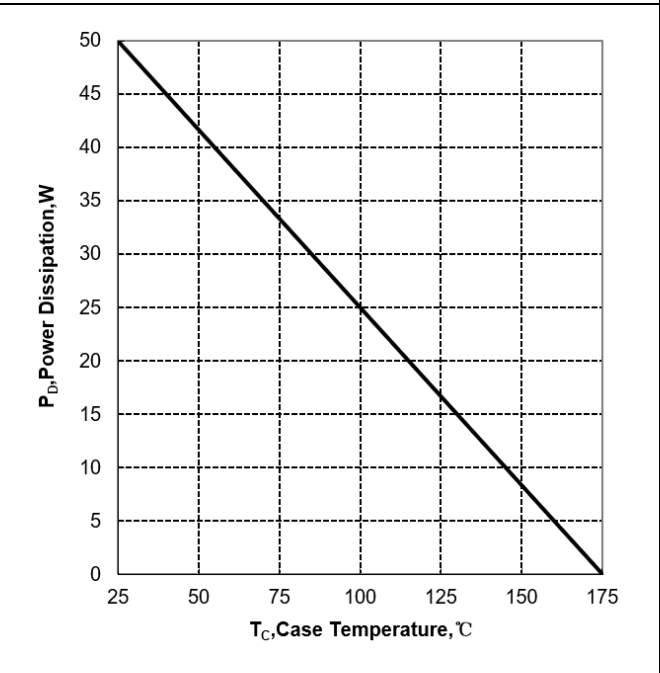


Figure 5. Collector Current vs Case Temperature for TO247/TO3PN

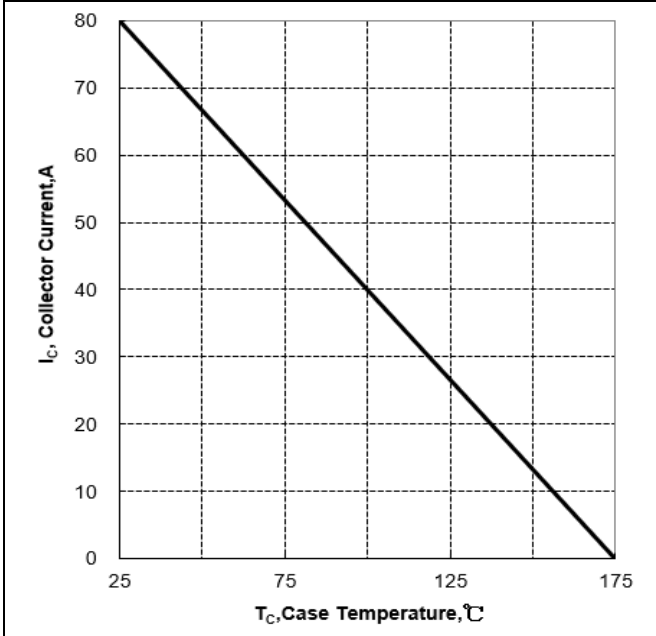


Figure 6. Collector Current vs Case Temperature for TO3PF

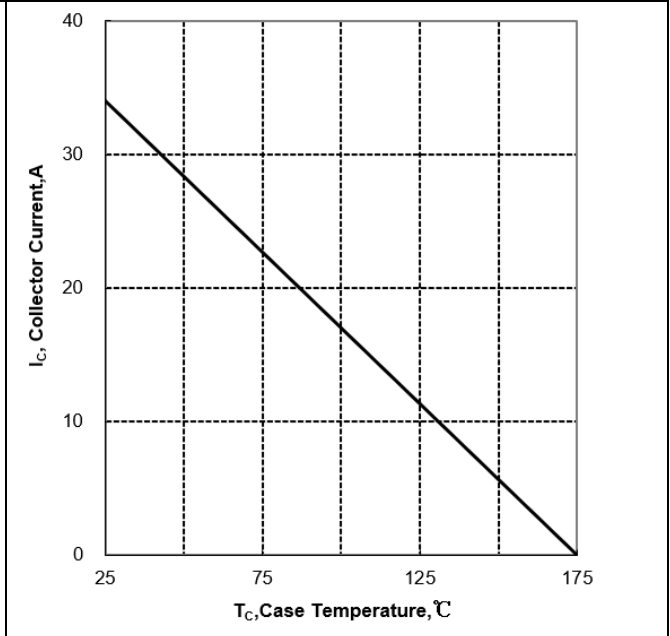


Figure 7. Typical Output Characteristics ($T_J=25^\circ\text{C}$)

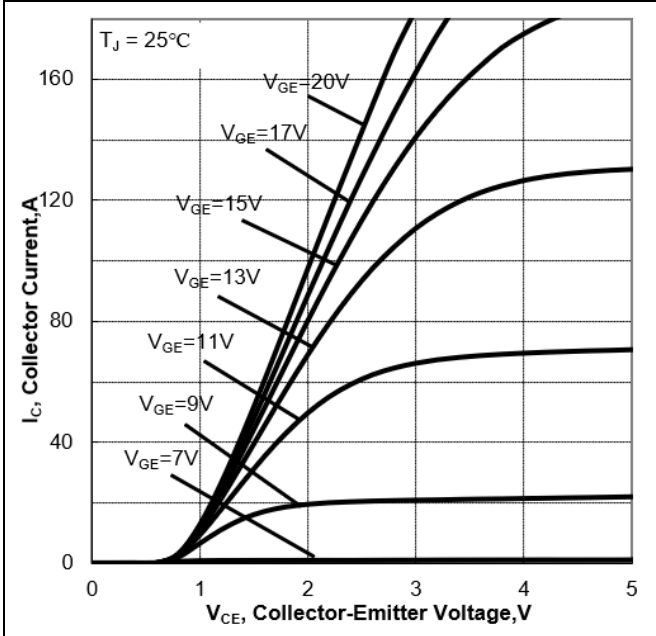


Figure 8. Typical Output Characteristics ($T_J=175^\circ\text{C}$)

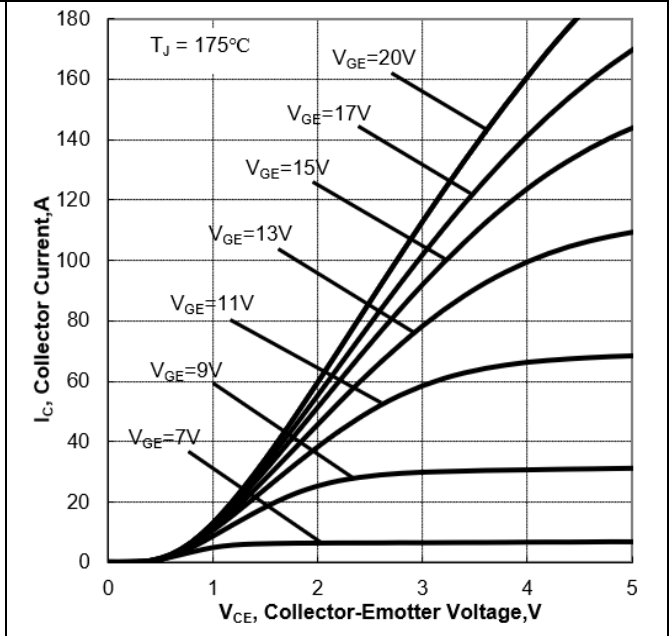


Figure 9. Typical Collector-Emitter Saturation Voltage vs Junction Temperature

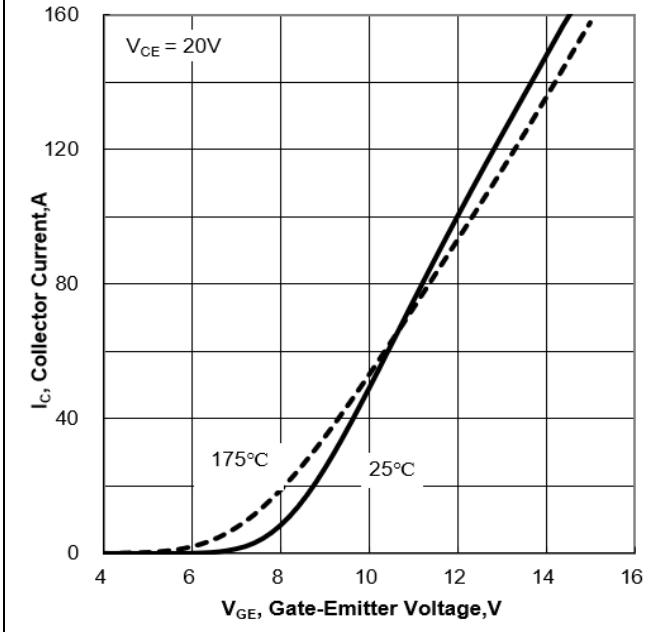


Figure 10. Typical Gate-Emitter Threshold Voltage vs Junction Temperature

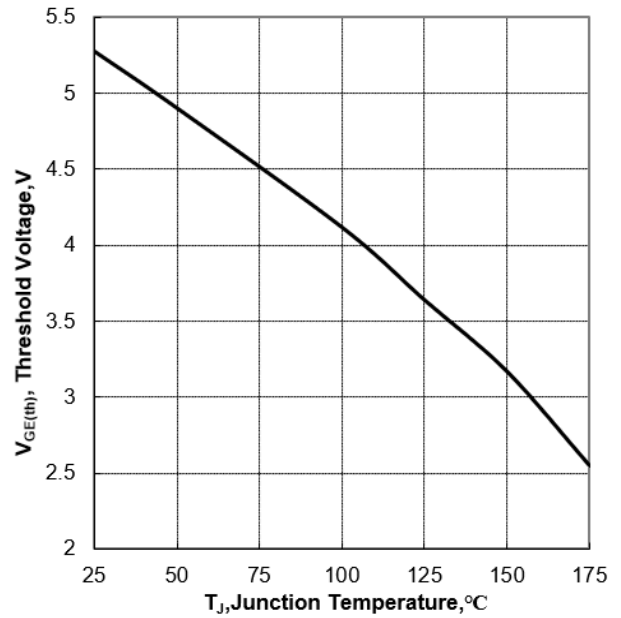


Figure 11. Typical Collector-Emitter Saturation Voltage vs Junction Temperature

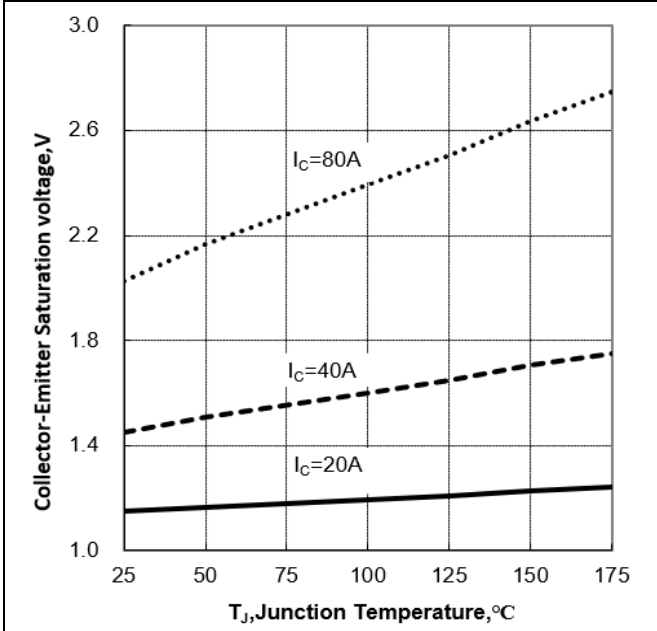


Figure 12. Typical Diode Forward Current vs Forward Voltage

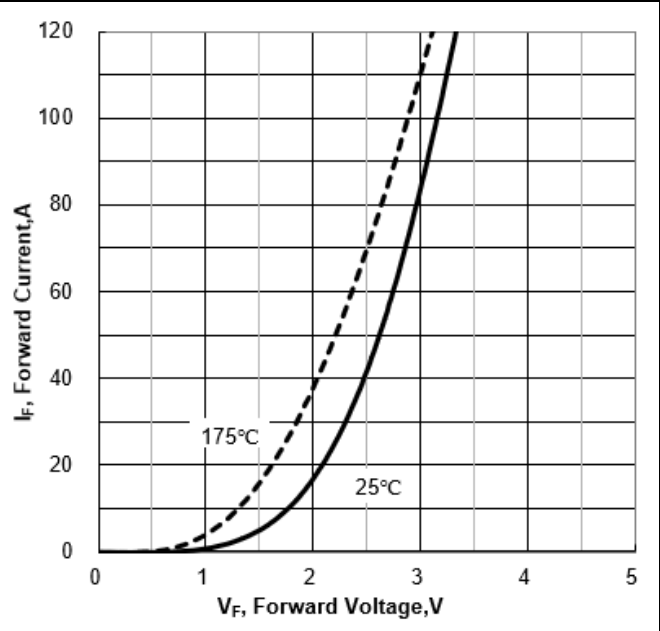


Figure 13. Typical Switching Times vs Gate Resistor ($T_J=25^\circ\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=40\text{A}$)

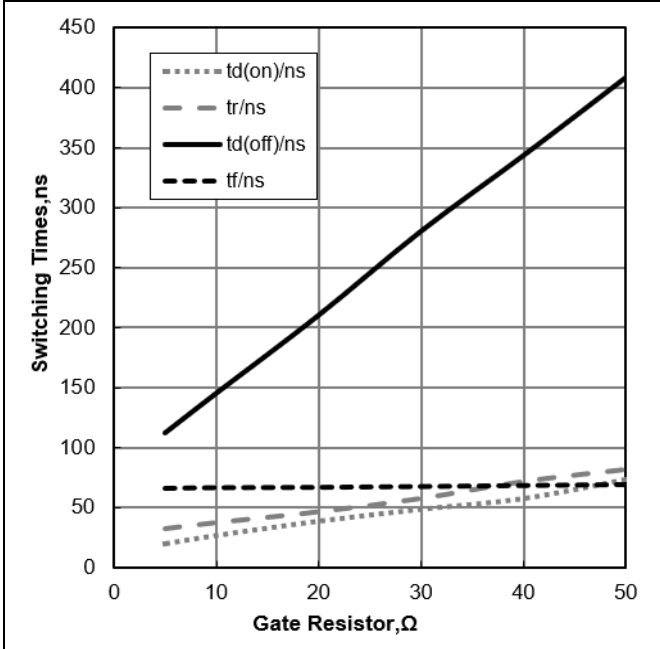


Figure 14. Typical Switching Energy vs Gate Resistor ($T_J=25^\circ\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=40\text{A}$)

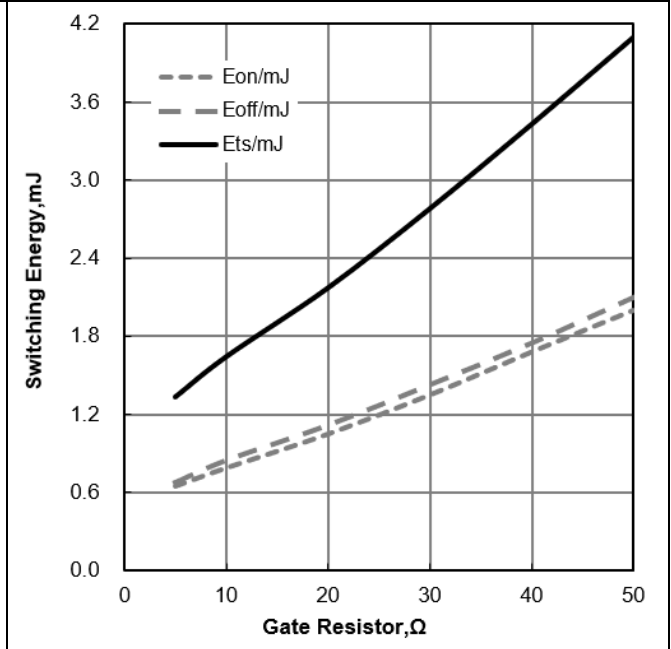


Figure 15. Typical Switching Times vs Junction Temperature ($V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=40\text{A}$)

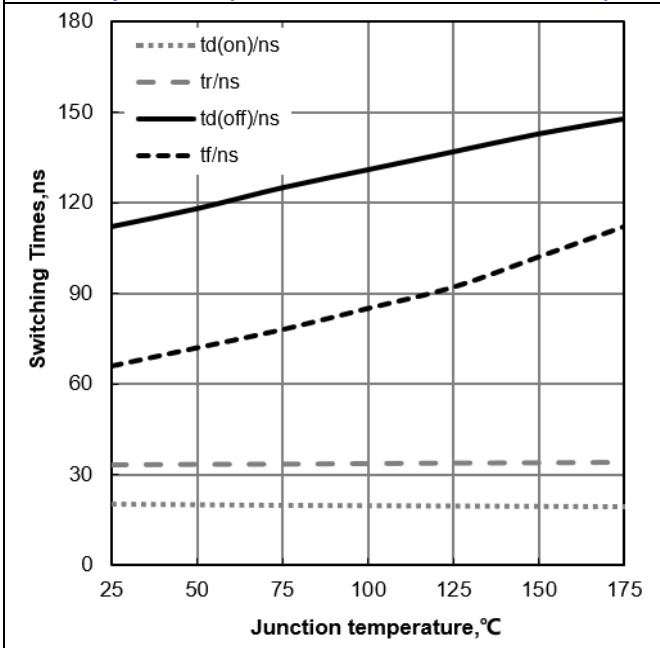


Figure 16. Typical Switching Energy vs Junction Temperature ($V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$, $I_C=40\text{A}$)

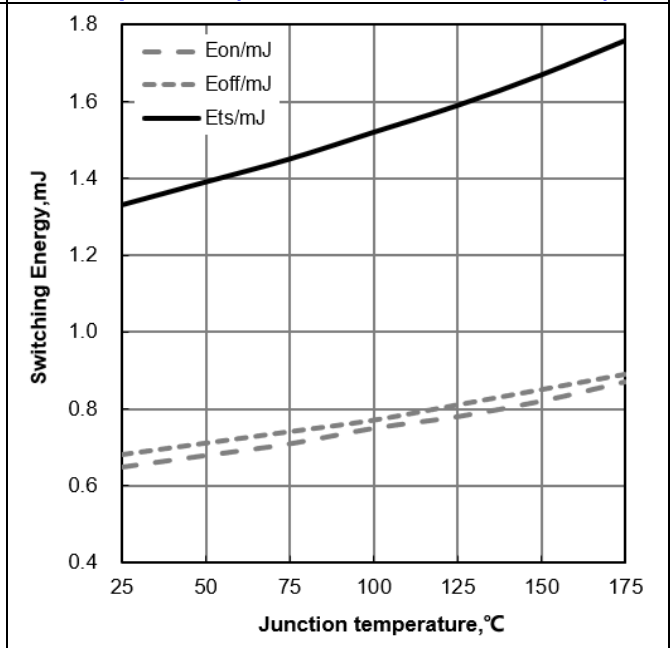


Figure 17. Typical Switching Times vs Collector Current ($T_J=25^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$)

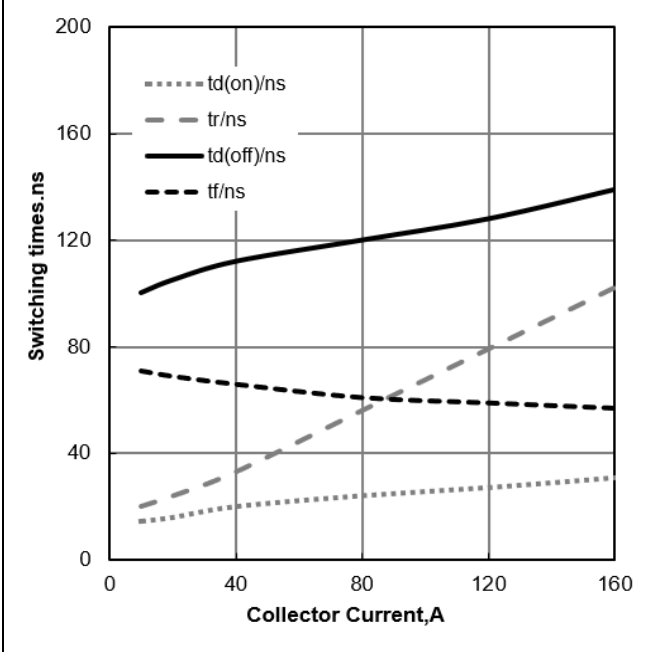


Figure 18. Typical Switching Energy vs Collector Current ($T_J=25^{\circ}\text{C}$, $V_{CE}=400\text{V}$, $V_{GE}=15/0\text{V}$)

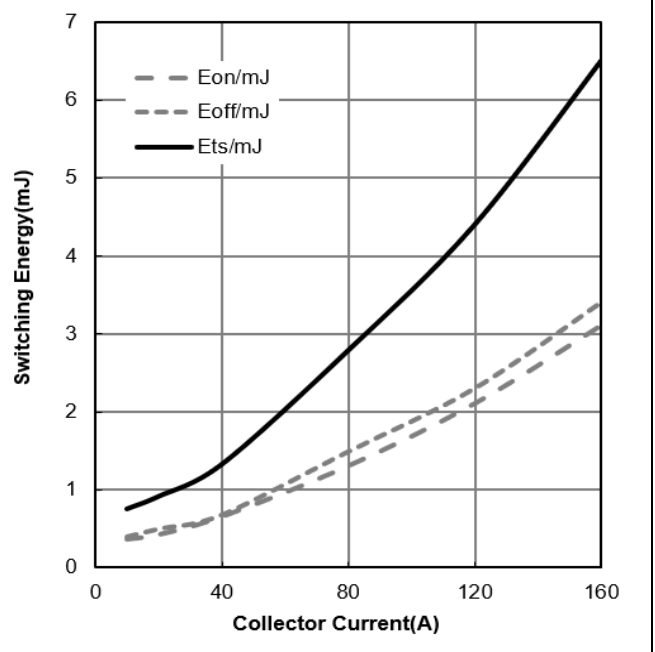


Figure 19. Typical Switching Times vs V_{CE} ($T_J=25^{\circ}\text{C}$, $V_{GE}=15/0\text{V}$, $I_C=40\text{A}$)

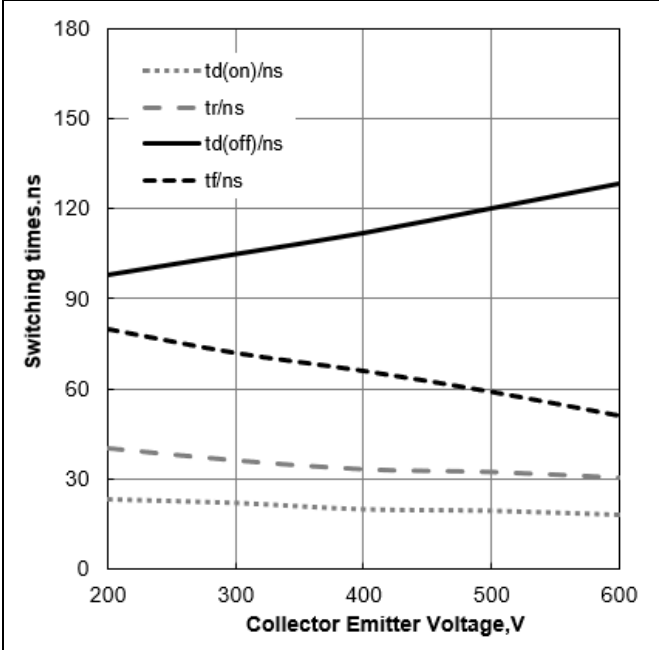


Figure 20. Typical Switching Energy vs V_{CE} ($T_J=25^{\circ}\text{C}$, $V_{GE}=15/0\text{V}$, $I_C=40\text{A}$)

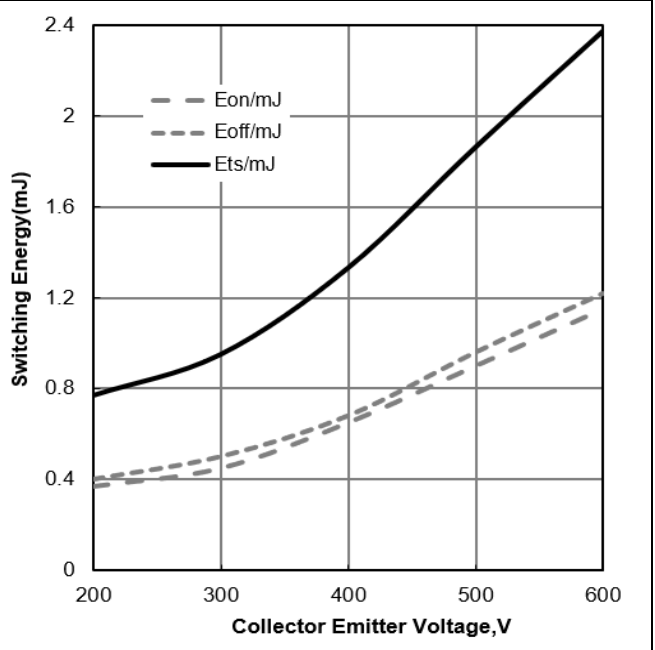


Figure 21. Typical Gate Charge

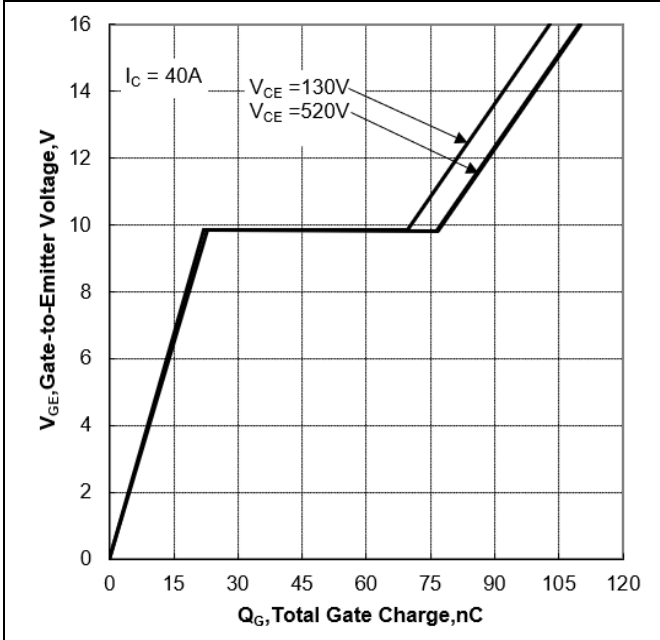


Figure 22. Typical Capacitance vs Collector-Emitter Voltage

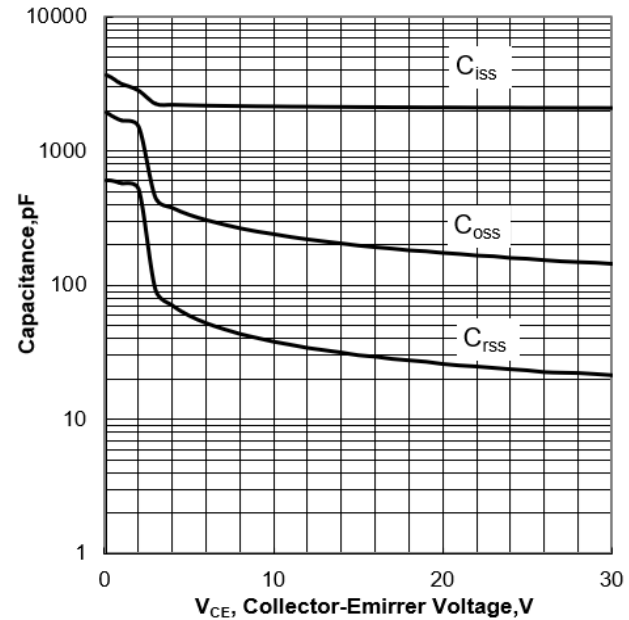


Figure 23. IGBT Transient Thermal Impedance vs Pulse Width (TO247/TO3PN)

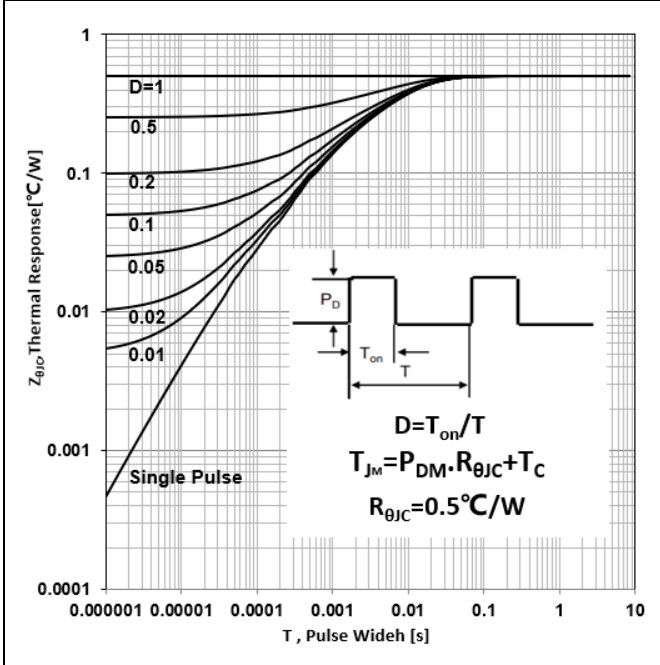


Figure 24. Diode Transient Thermal Impedance vs Pulse Width (TO3PF)

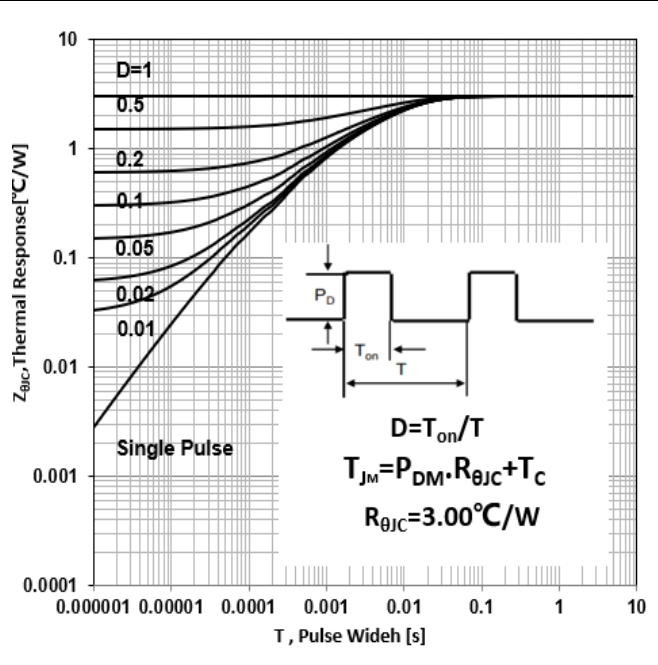


Figure 25. IGBT Transient Thermal Impedance vs Pulse Width(TO247/TO3PN)

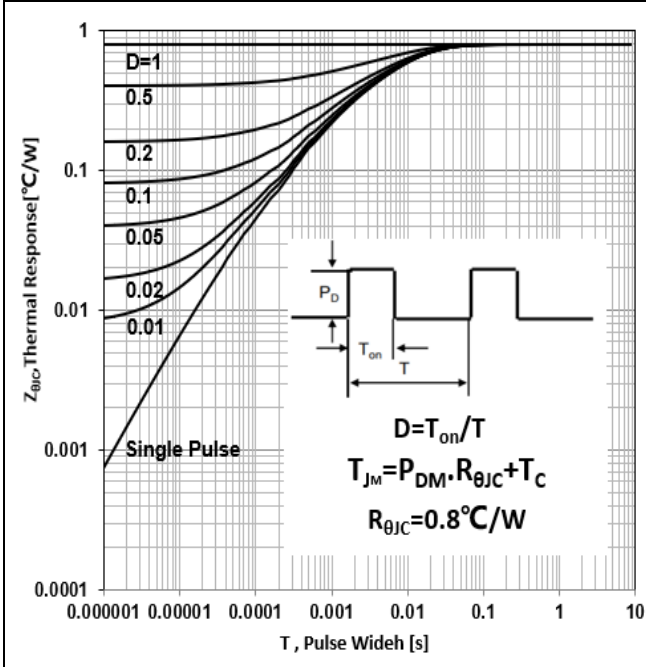
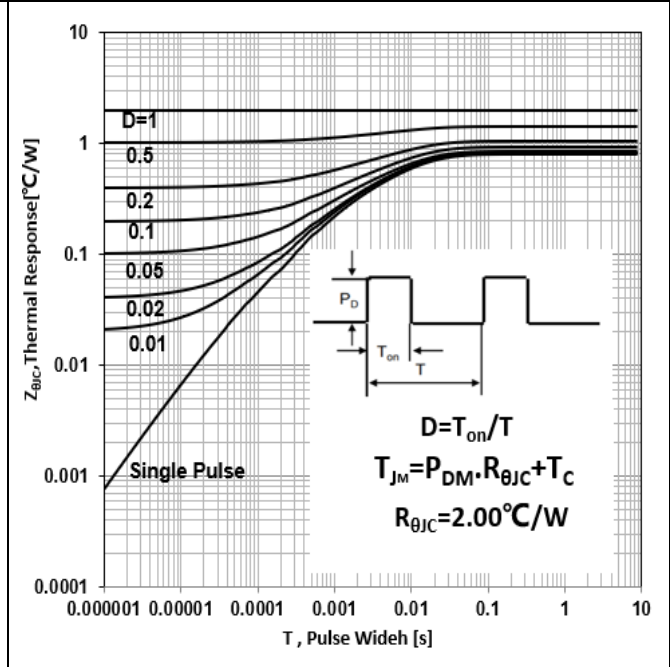
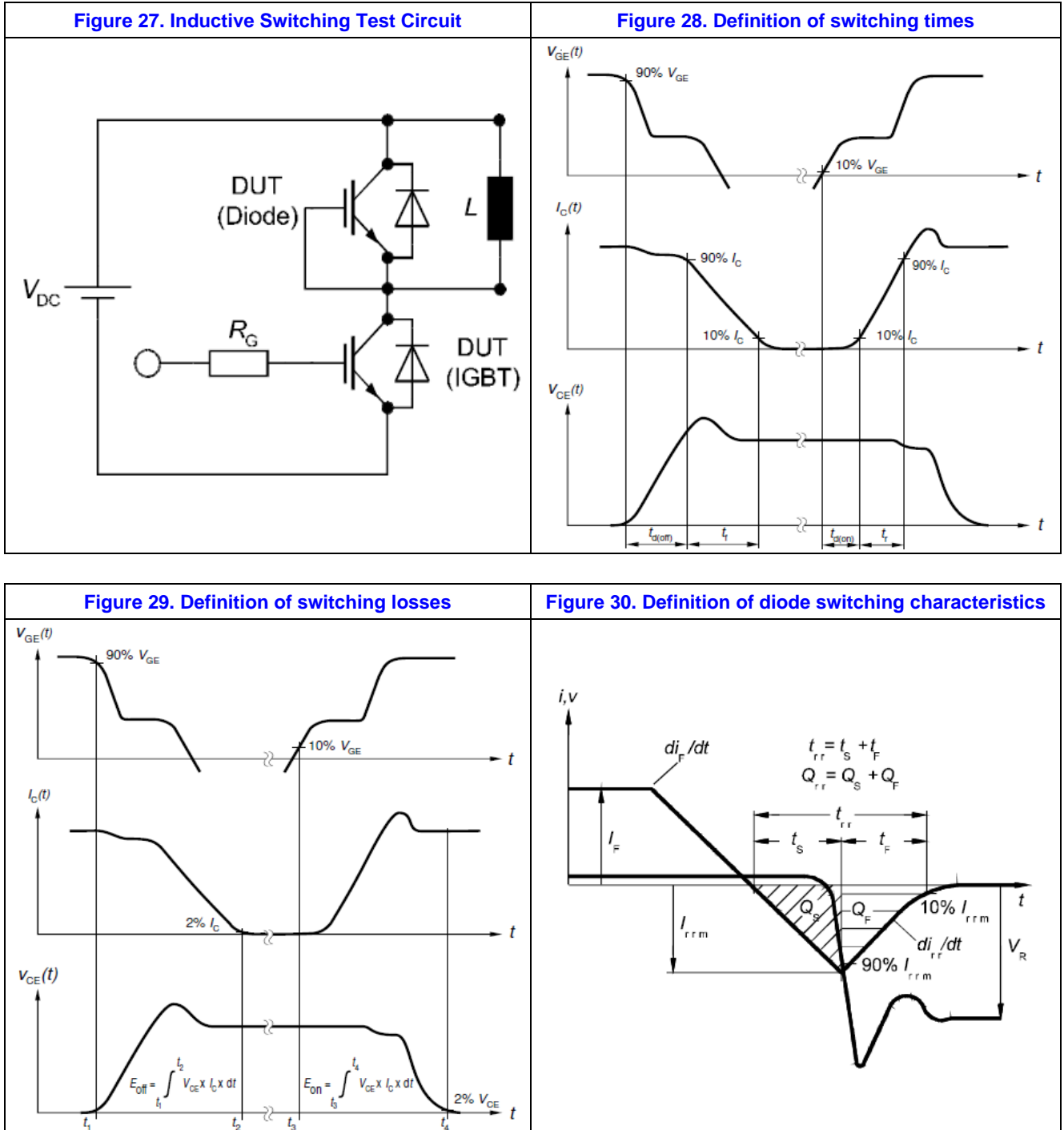


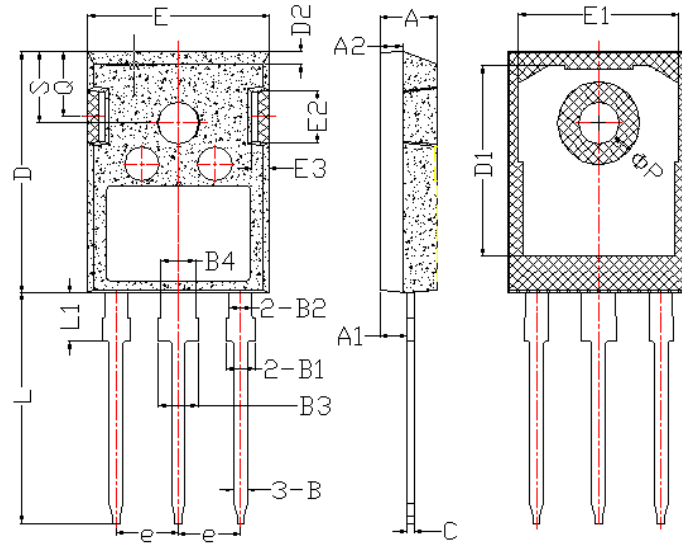
Figure 26. Diode Transient Thermal Impedance vs Pulse Width (TO3PF)



6. Test Circuit and Waveform

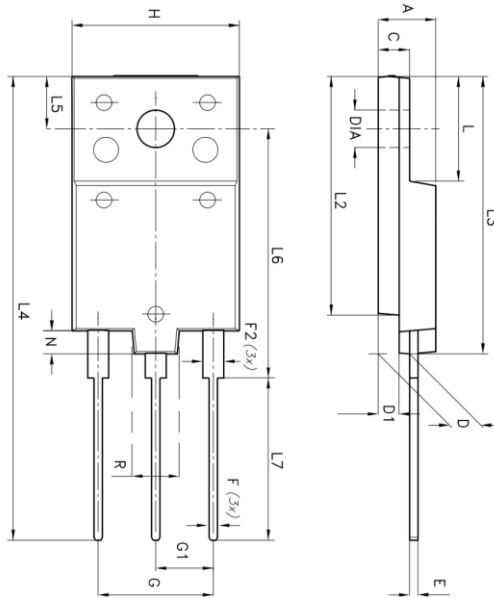


7. Package Description



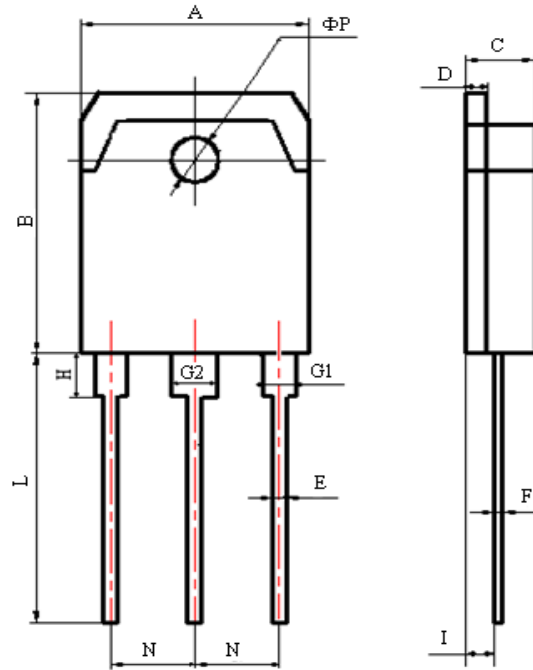
TO-247 Package

Items	Values(mm)	
	MIN	MAX
A	4.90	5.16
A1	2.27	2.53
A2	1.85	2.11
B	1.07	1.33
B1	1.90	2.41
B2	1.75	2.15
B3	2.87	3.38
B4	2.87	3.13
C	0.55	0.68
D	20.82	21.10
D1	16.25	17.65
D2	1.05	1.35
E	15.70	16.03
E1	13.10	14.15
E2	3.68	5.10
E3	1.68	2.60
e	5.44	
L	19.80	20.31
L1	4.17	4.47
ΦP	3.50	3.70
Q	5.49	6.00
S	6.04	6.30



TO-3PF Package

Items	Values(mm)	
	MIN	MAX
A	5.30	5.70
C	2.80	3.20
D	3.10	3.50
D1	1.80	2.20
E	0.80	1.10
F	0.65	0.95
F2	1.80	2.20
G	10.30	11.50
G1	5.45	
H	15.30	15.70
L	9.80	10.20
L2	22.80	23.20
L3	26.30	26.70
L4	43.20	44.40
L5	4.3	4.70
L6	24.3	24.70
L7	14.6	15
N	1.8	2.2
R	3.8	4.2
Dia	3.4	3.8



TO-3PN Package

Items	Values(mm)	
	MIN	MAX
A	15.00	16.00
B	19.20	20.60
C	4.60	5.00
D	1.40	1.60
E	0.90	1.10
F	0.50	0.70
G1	2.00	2.20
G2	3.00	3.20
H	3.00	3.70
I	1.20	1.70
	2.70	2.90
L	19.00	21.00
N	5.25	5.65
ΦP	3.10	3.30